EXAMPLES.

[0010]

The hollow sealing resin sheet preferably has a dynamic viscosity of 5000 to ~~20000~~ 30000 Pa·s both inclusive at 80°C before cured. This manner makes it possible to make the following compatible with each other more satisfactorily: sure retention of the hollow structure; and the property of the sheet that follows irregularities in portions other than the hollow structure. A method for measuring the dynamic viscosity is according to the description of EXAMPLES.

[0011]

In the hollow sealing resin sheet, the inorganic filler is preferably silica particles, alumina particles, or a mixture of these particles. This manner makes it possible to lower the linear expansion coefficient of the sheet after the sheet is cured to yield a highly reliable package.

[0012]

The present invention also includes a production method for a hollow package, including:

a laminating step of laminating the hollow sealing resin sheet over one or more electronic devices arranged on an adherend to cover the electronic devices while a hollow region is maintained between the adherend and the electronic devices; and

a sealed body forming step of curing the hollow sealing